



ALD8700S SERIES Full 3D Automatic Optical Inspection

Breaking limits in AOI technology in speed, performance and ease of use

- ► Top accuracy and precision
- Industry leading speed
- Fast and easy operation
- SMART algorithms
- Powerful debug-free OCR



IPC BASED FULL 3D MEASUREMENT AOI

High-range, precise, shadow-free 3D height measurement of solder joints and components coupled with simultaneous high-resolution, high-quality 2D images. 100% board coverage including the smallest parts.

Unique optical system developed by ALeader delivers an accurate, reliable 3D measurement without compromising 2D image quality

- 4-direction structured light (developed in-house, advanced phase-shifting digital projection system)
- Multi-directional (360° horizontal, 0-90° vertical) LED illumination system

• High-speed telecentric camera



Inspection pass-fail criteria complies with IPC-610 standard for shift and solder fillet measurement

Tolerances defined according to IPC level (dependent of pad size)



Best-in-industry component marking recognition





Easy programming. Friendly and intuitive user interface.

- Visualized and transparent definitions, no "black box", no "special" algorithms
- Defect samples are not required for creating a program without escapes
- Al based auto-programming



- Central library with part number and package links
- Simple and fast definition of non-standard components
- Over 90% of the program can be done offline

Insensitivity to the Component's and PCB Color

ALeader's AOI is capable of inspecting PCBs of any color. No user adjustments are required during program creation and tuning. The color of the component does not reduce the system's accuracy; however it serves wrong component and polarity detection, as well as other inspections.



Inspection result verification



- Ensures the operator will not miss the defect detected by AOI
- Easy to find component location on the PCB
- Clear component top and 3D interactive image for reliable verification
- · A real board is not required for decision making
- Inspection history review
- Operator feedback
- Possibility to use one repair station for multiple AOI machines

Process control

- Real-time SPC charts
- History review and analysis
- Cp, Cpk, GR&R
- Traceability
- Reports







- One-click solution for OCV/OCR and body color definition
- Easy setup of skipped components
- Effective debugging procedures

Inspection method Phase Measurement Profilometry Camera 12MPix high speed intelligent camera, telecentric lens Lighting system 4-directional structured light digital projection, top and 360° steep color LED light Program creation CAD and Gerber files import, Central Library, Part Number links, Auto Programming, Central Library Operation system Windows 10 Professional (64 bit) Inspection board specification Inspection board specification PCB type All colors and all pad finishes PCB size Min 50mm x 50mm, Max 450mm x 500mm (ALD8710S) 650mm x 710mm (ALD8730S) 1500mm x 450mm (ALD8750S) 450 x 330/610mm (ALD8710D) 650mm x 330/610mm (ALD8730D) PCB thickness range 0.2mm to 7mm PCB weight Up to 3kg Maximum PCB warpage +/- 5mm Clamping system edge clearance 50/40 mm (ALD8710S, ALD8730S), 65/40 mm (ALD8750S), 40/40 mm (ALD8710D, ALD8730D) Min component size 03015 (metric), 0.3mm pitch Inspection performance Resolution Resolution Top - 14µ (10µ, 7µ - option), Height – 0.7µ Height measurement range upto 20mm Speed Less than 600ms/FOV FOV size 56.00 x 42.00 mm (14µ), 40.96 x 30.72 mm (10µ), 28.67 x 21.50 mm (7µ) Inspection coverag	Functional specification		
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opporter reactives and programs, main bounds include bad many and many opporter includes	Special features	Supports auto-change programs, multi-boards (include bad mark) and multiprogram inspection modes	
Barcode system Auto-read barcode with camera - 1D and 2D; External reader scans back side barcode (option)	Barcode system	Auto-read barcode with camera - 1D and 2D; External reader scans back side barcode (option)	
Server mode Central server, multiple machines data handling	Server mode	Central server, multiple machines data handling	
Remote control Remote control through TCPIP for verification, system operation and program adjustment	Remote control	Remote control through TCPIP for verification, system operation and program adjustment	
Additional options SPC, repair station, offline programming station, external barcode scanner, support pins Support applications - Site Dashboard, First Article Inspection, Package Link	Additional options	SPC, repair station, offline programming station, external barcode scanner, support pins Support applications - Site Dashboard, First Article Inspection, Package Link	
Hardware	Hardware		
Conveyor Flat belt conveyor, automatic clamp (pneumatic), auto load and unload, automatic width adjustment	Conveyor	Flat belt conveyor, automatic clamp (pneumatic), auto load and unload, automatic width adjustment	
Conveyor direction/time Left to Right or Right to Left, in\out time 4 sec	Conveyor direction/time	Left to Right or Right to Left, in\out time 4 sec	
X/Y driver Screw and AC server driver. PCB fix, camera moves X/Y	X/Y driver	Screw and AC server driver. PCB fix, camera moves X/Y	
Display 23.6 inch, touch screen	Display	23.6 inch, touch screen	
Power supply AC230V 50/60Hz, <1.5 KVA	Power supply	AC230V 50/60Hz, <1.5 KVA	
Compressed air 0.4-0.8 MPA	Compressed air	0.4-0.8 MPA	
Equipment communication SMEMA	Equipment communication	SMEMA	
Operational conditions 10-35°C, 35~80% RH (no dew)	Operational conditions	10-35°C, 35~80% RH (no dew)	
Dimension and Weight	Dimension and Weight		
Weight 920kg (ALD8720S), 1150kg (ALD8730S)	Weight	920kg (ALD8720S), 1150kg (ALD8730S)	
Dimensions 1000x1340x1610 (ALD8710S), 1000x1540x1610 mm (ALD8710D), 1200x1540x1610mm (ALD8730S, ALD8730D), 2100x1210x1550 mm (ALD8750S)870-970mm	Dimensions	1000x1340x1610 (ALD8710S), 1000x1540x1610 mm (ALD8710D), 1200x1540x1610mm (ALD8730S, ALD8730D), 2100x1210x1550 mm (ALD8750S)870-970mm	
Conveyor height 880-950mm	Conveyor height	880-950mm	

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Above specifications are subject to change without notice. Images used in the brochure are for illustrative purposes only.

System footprint dimensions are shown for model ALD8730S. For other models please refer to the specification table



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